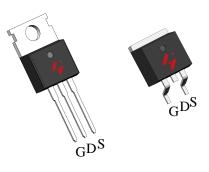


#### N-Channel Enhancement Mode MOSFET

#### **Features**

- 30V/290A $R_{DS(ON)}=1.6m\Omega(typ.)$  @VGS = 10V
- 100% avalanche tested
- Excellent CdV/dt effect decline
- Lead Free Device Available

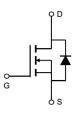
### **Pin Description**



TO-220FB-3L TO-263-2L

### **Applications**

- Switching Application
- Power Management for DC/DC



N-Channel MOSFET

### Ordering and Marking Information



Package Code

P : TO-220FB-3L

Date Code YYXXX WW B: TO-263-2L

Assembly Material G: Lead Free Device

Note: HUAYI lead -free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI lead -free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature. HUAYI defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this pr-oduct and/or to this document at any time without notice.

# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit	
Common I	Ratings (T <sub>C</sub> =25°C Unless Otherwise Noted)			•
V <sub>DSS</sub>	Drain-Source Voltage	30	V	
V <sub>GSS</sub>	Gate-Source Voltage		±20	
TJ	Maximum Junction Temperature		175	°C
T <sub>STG</sub>	Storage Temperature Range		-55 to 175	°C
Is	Diode Continuous Forward Current T <sub>C</sub> =25°C		290	А
Mounted o	on Large Heat Sink	•		
I <sub>DM</sub>	Pulsed Drain Current *	T <sub>C</sub> =25°C	1000**	А
	Continuous Drain Current	T <sub>C</sub> =25°C	290	A
l I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> =100°C	200	
В	T <sub>C</sub> =25°C	T <sub>C</sub> =25°C	214	W
P <sub>D</sub>	Maximum Power Dissipation T <sub>c</sub> =100°C		107	VV
R <sub>θJC</sub>	Thermal Resistance-Junction to Case	0.7	°C/W	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		62.5	°C/W
E <sub>AS</sub>	Avalanche Energy,Single Pulsed L=0.5mH		1325***	mJ

Note: \* Repetitive rating; pulse width limited by junction temperature 
\*\* Drain current is limited by junction temperature

# **Electrical Characteristics** (T<sub>c</sub> = 25°C Unless Otherwise Noted)

Complete	Doromotor	Test Conditions -		HY4903			11:0:4
Symbol	Parameter			Min.	Тур.	Max.	Unit
Static Ch	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA		30	-	-	V
,	Zoro Coto Voltago Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V		-	-	1	Α
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	T <sub>J</sub> =8	35°C	-	-	30	μА
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{DS}=250\mu$ A	1	1.0	-	3.0	V
I <sub>GSS</sub>	Gate Leakage Current	$V_{GS}=\pm20V, V_{DS}=0V$		-	-	±100	nA
D *	Drain Course On state Besistense	V <sub>GS</sub> =10V, I <sub>DS</sub> =145A		-	1.6	2.0	mΩ
R <sub>DS(ON)</sub> *	Drain-Source On-state Resistance V <sub>GS</sub> =4.5V, I <sub>DS</sub> =145A			2.0	3.0	mΩ	
Diode Ch	Diode Characteristics						
V <sub>SD</sub> *	Diode Forward Voltage	I <sub>SD</sub> =145 A, V <sub>GS</sub> =0V		-	0.8	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	1 11E A all /dt 11	20.4/	-	38	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$ I_{DS}$ =145A, $dI_{SD}/dt$ =100A/ $\mu$ S		-	80	-	nC

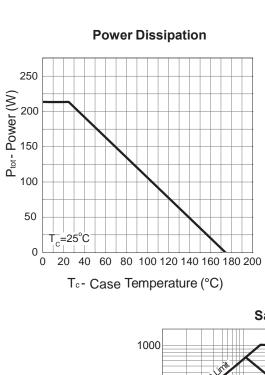
<sup>\*\*\*</sup> VD=24V

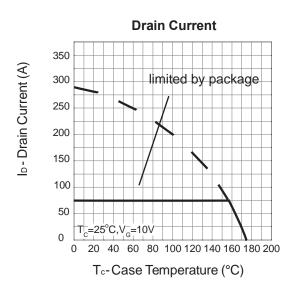
# **Electrical Characteristics (Cont.)** $(T_c = 25^{\circ}C \text{ Unless Otherwise Noted})$

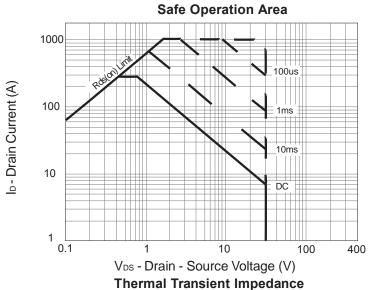
Symbol	Parameter	Test Conditions	HY4903			Unit	
Symbol	Farameter	rest Conditions	Min.	Тур.	Max.	Jill	
Dynamic	Characteristics						
$R_{G}$	Gate Resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,F=1MHz	-	0.5	-	Ω	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,	-	11506	-		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V,	-	1236	-	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance	Frequency=1.0MHz	ı	762	-		
t <sub>d(ON)</sub>	Turn-on Delay Time	$V_{DD}$ =15V, $R_{G}$ =3.3 $\Omega$ $I_{DS}$ =145A, $V_{GS}$ =10 V,	ı	52	ı		
T <sub>r</sub>	Turn-on Rise Time		1	120	-	ns	
t <sub>d(OFF)</sub>	Turn-off Delay Time		ı	90	1	113	
T <sub>f</sub>	Turn-off Fall Time		ı	78	•		
Gate Cha	Gate Charge Characteristics						
Qg	Total Gate Charge	V <sub>DS</sub> =24V, V <sub>GS</sub> =10 V, I <sub>DS</sub> =145A	-	247	-		
Q <sub>gs</sub>	Gate-Source Charge		-	27	-	nC	
$Q_{gd}$	Gate-Drain Charge			58	-		

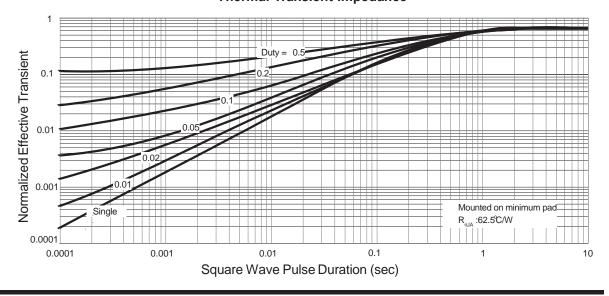
Note \* : Pulse test ; pulse width  $\leq\!300\mu\text{s},$  duty cycle  $\!\leq\!2\%.$ 

### **Typical Operating Characteristics**



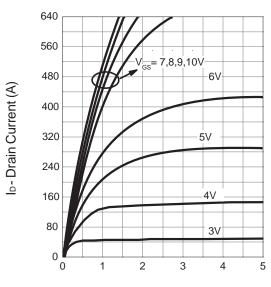






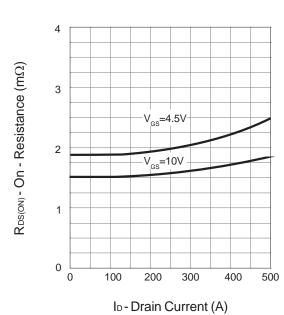
# **Typical Operating Characteristics (Cont.)**

**Output Characteristics** 

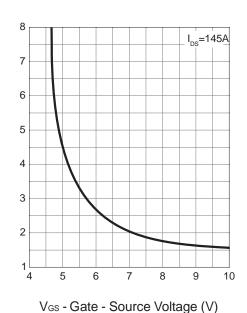


V<sub>DS</sub> - Drain-Source Voltage (V)

#### **Drain-Source On Resistance**

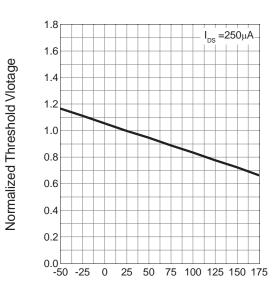


**Drain-Source On Resistance** 



RDS(ON) - On - Resistance (mΩ)

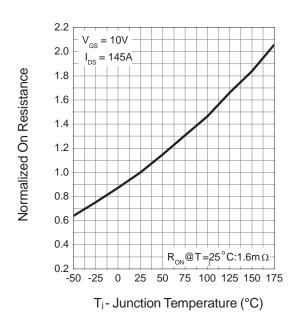
**Gate Threshold Voltage** 



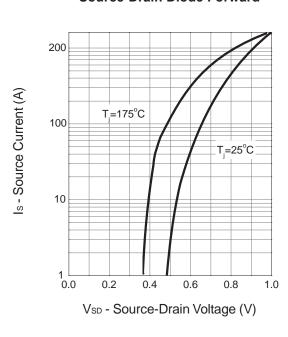
T<sub>j</sub> - Junction Temperature (°C)

# **Typical Operating Characteristics (Cont.)**

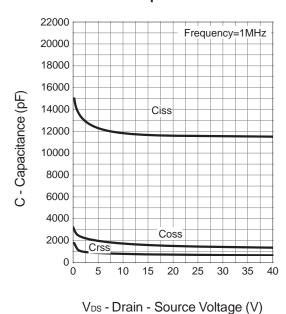
#### **Drain-Source On Resistance**



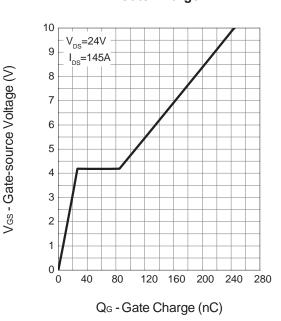
#### **Source-Drain Diode Forward**



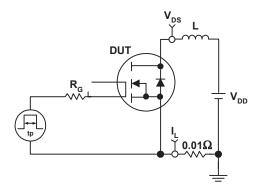
#### Capacitance

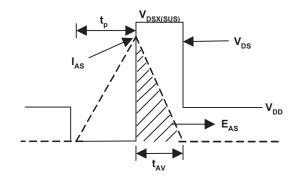


#### **Gate Charge**

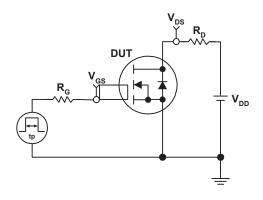


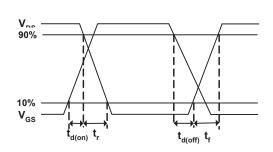
## **Avalanche Test Circuit**





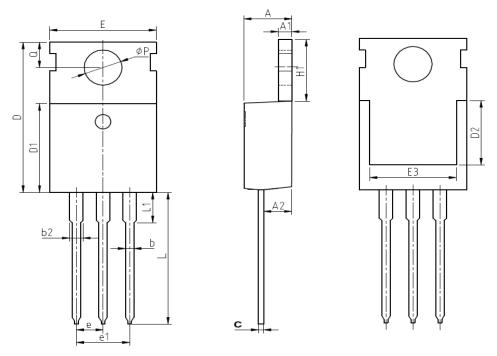
# **Switching Time Test Circuit**





# **Package Information**

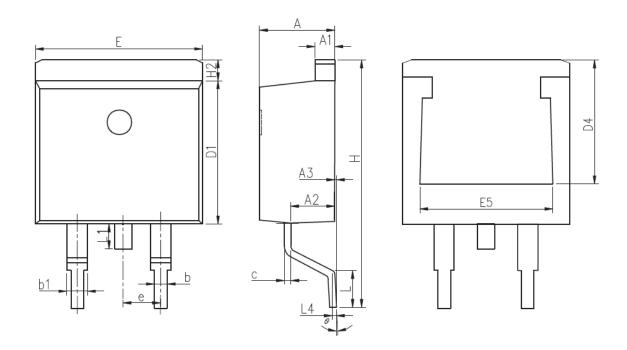
TO-220FB-3L



### COMMON DIMENSIONS

mm			
SYMBOL	MIN	N	MAX
Α	4.37	4.57	4.77
A1	1.25	1.30	1.45
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
С	0.40	0.50	0.65
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
Е	9.70	10.00	10.30
E3	7.00	-	-
е		2.54 BSC	
e1		5.08 BSC	
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ФР	3.40	3.60	3.80
Q	2.60	2.80	3.00

### TO-263-2L



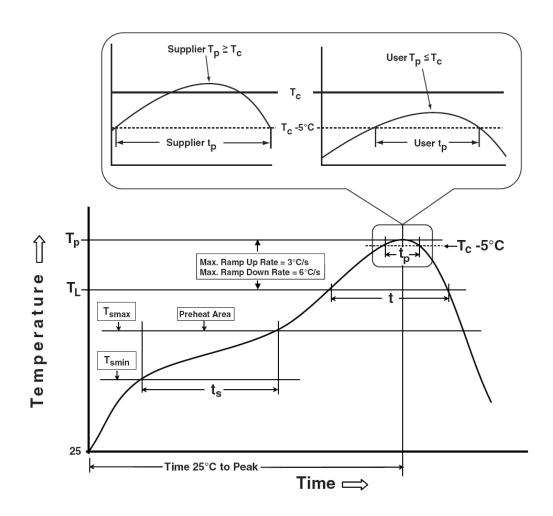
### COMMON DIMENSIONS

OGINIMON DIMENSIONS				
SYMBOL	mm			
STIVIBOL	MIN	NOM	MAX	
А	4.37	4.57	4.77	
A1	1.22	1.27	1.42	
A2	2.49	2.69	2.89	
A3	0	0.13	0.25	
b	0.7	0.81	0.96	
b1	1.17	1.27	1.47	
С	0.3	0.38	0.53	
D1	8.5	8.7	8.9	
D4	6.6	-	-	
Е	9.86	10.16	10.36	
E5	7.06	-	-	
е		2.54 BSC		
Н	14.7	15.1	15.5	
H2	1.07	1.27	1.47	
L	2	2.3	2.6	
L1	1.4	1.55	1.7	
L4	0.25 BSC			
θ	0°	5°	9°	

### **Devices Per Unit**

Package Type	Unit	Quantity
TO-220FB-3L	Tube	50
TO-263-2L	Tube	50

# **Classification Profile**



#### **Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds	
Average ramp-up rate (T <sub>smax</sub> to T <sub>P</sub> )	3 °C/second max.	3°C/second max.	
Liquidous temperature (T <sub>L</sub> ) Time at liquidous (t <sub>L</sub> )	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body Temperature $(T_p)^*$	See Classification Temp in table 1	See Classification Temp in table 2	
Time (t <sub>P</sub> )** within 5°C of the specified classification temperature (T <sub>c</sub> )	20** seconds	30** seconds	
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6 °C/second max.	6 °C/second max.	
Time 25°C to peak temperature	6 minutes max.	8 minutes max.	
* Tolerance for peak profile Temperature (T <sub>p</sub> ) is defined as a supplier minimum and a user maximum.  ** Tolerance for time at peak profile temperature (t <sub>p</sub> ) is defined as a supplier minimum and a user maximum.			

I olerance for time at peak profile temperature  $(t_p)$  is defined as a supplier minimum and

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

### **Reliability Test Program**

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168 Hrs /500 Hrs /1000 Hrs, Bias @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -55°C~150°C

#### **Customer Service**

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